## Amendment to the Abstract

Please amend the abstract to read:

--A process of manufacturing printed circuit boards containing both areas of thick conductive traces and areas of fine resolution conductors in a single conductive layer, and printed circuit boards formed from such a process. A conductive core is first fabricated containing areas of thick conductors on a relatively thin conductive base. The conductive core is then bonded to a sublayer with the thick conductive areas adjacent to the sublayer in order to form a relatively flat laminate. After bonding, the conductive surface of the laminate is formed into printed conductor traces by methods known in the art. In various embodiments of the invention a solder mask coating is applied to the completed printed circuit board. By use of this process, a single layer printed circuit comprising both thick conductor traces and fine resolution traces is possible.--